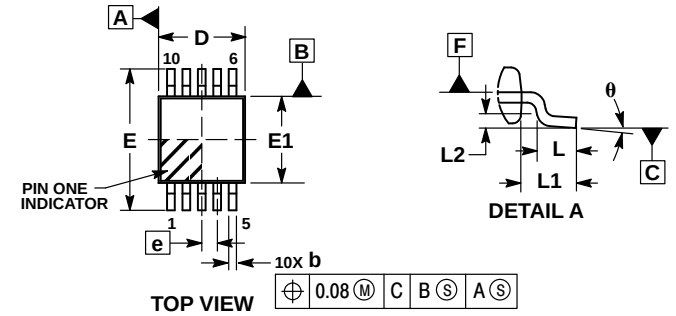
MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

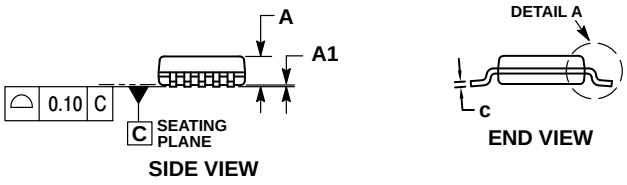
ON Semiconductor®

SCALE 1:1

MSOP10, 3x3
CASE 846AE
ISSUE A

DATE 20 JUN 2017

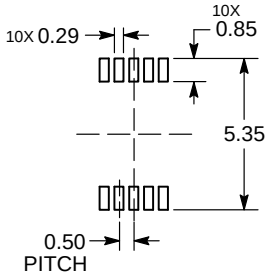




NOTES:
1. DIMENSIONS AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSIONS: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.10 MM IN EXCESS OF MAXIMUM MATERIAL CONDITION.
4. DIMENSION D DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.15 MM PER SIDE. DIMENSION E DOES NOT INCLUDE INTER-LEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 MM PER SIDE. DIMENSIONS D AND E ARE DETERMINED AT DATUM F.
5. DATUMS A AND B TO BE DETERMINED AT DATUM F.
6. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

	MILLIMETERS		
DIM	MIN	NOM	MAX
A	–––	–––	1.10
A1	0.00	0.05	0.15
A2	0.75	0.85	0.95
b	0.17	–––	0.27
c	0.13	–––	0.23
D	2.90	3.00	3.10
E	4.75	4.90	5.05
E1	2.90	3.00	3.10
e	0.50 BSC		
L	0.40	0.70	0.80
L1	0.95 REF		
L2	0.25 BSC		
θ	0°	–––	8°

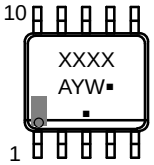
RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
W = Work Week
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present and may be in either location. Some products may not follow the Generic Marking.

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STATUS:	**ON SEMICONDUCTOR STANDARD**		
REFERENCE:			
DESCRIPTION:	**MSOP10, 3X3**		**PAGE 1 OF 2**

ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM POD #MSOP10−013−01 TO ON SEMICONDUCTOR. REQ. BY B. BERGMAN.	19 DEC 2008
A	MODIFIED DRAWING TO ON SEMICONDUCTOR JEDEC STANDARD AND ADDED SOLDERING FOOTPRINT. REQ. BY M. PREJZEK.	20 JUN 2017